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ISTFA 2017 TECHNICAL PROGRAM COMMITTEE



ISTFA 2017 Technical Program Chair

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GLOBALFOUNDRIES

Session Chairs

3D Device Failure Analysis

Claudia Keller, *Infineon*
Christian Schmidt, *Carl Zeiss X-ray
Microscopy*

Detecting and Preventing Counterfeit Microelectronics

Michael Woo, *Raytheon*
Luigi Chun, *Raytheon*

Fault Isolation

Kent Erington, *NXP Semiconductors*
Keith Serrels, *NXP Semiconductors*

Microscopy

Yu Zhu, *IBM*
Tom Schamp, *Hitachi High Technologies*

FIB Circuit Analysis and Edit

Ken Lagarec, *Contractor*
Ted Lundquist, *Fibics Incorporated*

Mixed Mode & High Power Devices Case Studies

Michael Bruce, *Consultant*
Stephen Fasolino, *Raytheon*

Electrical and Yield Tutorials

Gregory M. Johnson, *GlobalFoundries*
Randal E. Mulder, *Silicon Labs*

Microscopy Tutorials

Susan Li, *Cypress Semiconductor*
Rose Ring, *Kionix*

Board and System Level FA

Bhanu P. Sood, *NASA*
Jason Wheeler, *Raytheon*

Space Application FA

Ted Kolasa, *Orbital Sciences Corporation*
Richard Blank, *California Institute of
Technology*

Product Yield, Test and Diagnostics

Rao Desineni, *GlobalFoundries*
Sounil Biswas, *Cavium Inc.*

Nanoprobing and Electrical Characterization

John Sanders, *Thermo Fisher Scientific*
Sweta Pendyala, *GlobalFoundries*

Sample Preparation and Device Deprocessing

Erwin Hendarto, *Silicon Labs*
Jane Li, *NVIDIA*

FA Processes Case Studies

James Demarest, *IBM*
Andreas Meyer, *GlobalFoundries*

Fault Isolation Tutorials

Mayue Xie, *Intel*
Frank Altmann, *Fraunhofer Institute for
Mechanics of Materials*

Package and Physical Analysis Challenges Tutorials

Chris Richardson, *Allied High Tech Products*
John Bescup, *Weatherford Drilling Services*

Low Power Devices Case Studies

Szu Huat Goh, *GlobalFoundries*
Gil Garteiz, *Freescale Semiconductor*

Emerging FA Techniques and Concepts

Dan Bodoh, *NXP*
Christian Boit, *Technical University of
Berlin*

FIB Sample Preparation

Bryan Tracy, *Evans Analytical Group*
Haifeng Want, *Western Digital
Corporation*

Packaging and Assembly Level FA

Peng Li, *Intel Corporation*
Wentao Qin, *ON Semiconductor*

Scanning Probe Analysis

Phil Kaszuba, *GlobalFoundries*
Jocho Nxumalo, *GlobalFoundries*

Hardware Attacks, Security, and Reverse Engineering

Navid Asadi, *University of Florida*
Sahar Hihath, *DMEA*

Featured Talks Tutorials

Mark Jenkins, *Sandia National
Laboratories*
Corey Senowitz, *Qualcomm Technologies*